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Details

Product Status	Obsolete
Core Processor	HC08
Core Size	8-Bit
Speed	8MHz
Connectivity	-
Peripherals	LVD, POR, PWM
Number of I/O	5
Program Memory Size	1.5KB (1.5K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	8-VDFN Exposed Pad
Supplier Device Package	8-DFN-EP (4x4)
Purchase URL	https://www.e-xfl.com/pro/item?MUrl=&PartUrl=mc68hc908qt2cfq

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MC68HC908QY4 MC68HC908QT4 MC68HC908QY2 MC68HC908QT2 MC68HC908QY1 MC68HC908QT1

Data Sheet

To provide the most up-to-date information, the revision of our documents on the World Wide Web will be the most current. Your printed copy may be an earlier revision. To verify you have the latest information available, refer to:

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Memory

\$0000 ↓	I/O REGISTERS 64 BYTES		
\$003F			
\$0040 ↓ \$007F	RESERVED ⁽¹⁾ 64 BYTES	Note 1.	
\$0080 ↓ ¢00EE	RAM 128 BYTES	 Attempts to execute code from addresses in this range will generate an illegal address reset. 	
\$00FF \$0100 ↓	UNIMPLEMENTED ⁽¹⁾ 9984 BYTES		
\$27FF	000121120	_	
\$2800 ↓ \$2DFF	AUXILIARY ROM 1536 BYTES		
\$2E00 ↓ \$EDFF	UNIMPLEMENTED ⁽¹⁾ 49152 BYTES	UNIMPLEMENTED 51712 BYTES)0
\$EE00 ↓ \$FDFF	FLASH MEMORY MC68HC908QT4 AND MC68HC908QY4 4096 BYTES	FLASH MEMORY 1536 BYTES \$FDI \$FDI)0 FF
\$FE00	BREAK STATUS REGISTER (BSR)	MC68HC908OT1 MC68HC908OT2	
\$FE01	RESET STATUS REGISTER (SRSR)	MC68HC908QY1, and MC68HC908QY2	
\$FE02	BREAK AUXILIARY REGISTER (BRKAR)	Memory Map	
\$FE03	BREAK FLAG CONTROL REGISTER (BFCR)		
\$FE04	INTERRUPT STATUS REGISTER 1 (INT1)		
\$FE05	INTERRUPT STATUS REGISTER 2 (INT2)		
\$FE06	INTERRUPT STATUS REGISTER 3 (INT3)		
\$FE07	RESERVED FOR FLASH TEST CONTROL REGISTER (FLTCR)		
\$FE08	FLASH CONTROL REGISTER (FLCR)		
\$FE09	BREAK ADDRESS HIGH REGISTER (BRKH)		
\$FE0A	BREAK ADDRESS LOW REGISTER (BRKL)		
\$FE0B	BREAK STATUS AND CONTROL REGISTER (BRKSCR)		
\$FE0C	LVISR		
\$FE0D ↓ \$FE0F	RESERVED FOR FLASH TEST 3 BYTES		
\$FE10 ↓ \$FFAF	MONITOR ROM 416 BYTES		
\$FFB0 ↓ \$FFBD	FLASH 14 BYTES	-	
\$FFBE	FLASH BLOCK PROTECT REGISTER (FLBPR)	-	
\$FFBF	RESERVED FLASH		
\$FFC0	INTERNAL OSCILLATOR TRIM VALUE (VDD = 5.0 V)	-	
\$FFC1	INTERNAL OSCILLATOR TRIM VALUE (VDD = 3.0 V)	1	
\$FFC2 ↓	FLASH 14 BYTES		
\$FFD0 ↓ \$FFFF	USER VECTORS 48 BYTES		

Figure 2-1. Memory Map

NP

Memory

Addr.	Register Name		Bit 7	6	5	4	3	2	1	Bit 0
\$0006	Unimplemented									
\$000A	Unimplemented									
	p									
\$000B	Port A Input Pullup Enable Register (PTAPUE)	Read: Write:	OSC2EN	0	PTAPUE5	PTAPUE4	PTAPUE3	PTAPUE2	PTAPUE1	PTAPUE0
	See page 99.	Reset:	0	0	0	0	0	0	0	0
\$000C	Port B Input Pullup Enable Register (PTBPUE)	Read: Write:	PTBPUE7	PTBPUE6	PTBPUE5	PTBPUE4	PTBPUE3	PTBPUE2	PTBPUE1	PTBPUE0
	See page 102.	Reset:	0	0	0	0	0	0	0	0
\$000D ↓ \$0019	Unimplemented									
		I								
\$001A	Keyboard Status and Control Register (KBSCR)	Read: Write:	0	0	0	0	KEYF	0 ACKK	IMASKK	MODEK
	See page 83.	Reset:	0	0	0	0	0	0	0	0
\$001B	Keyboard Interrupt Enable Register (KBIER)	Read: Write:	0	AWUIE	KBIE5	KBIE4	KBIE3	KBIE2	KBIE1	KBIE0
	See page 84.	Reset:	0	0	0	0	0	0	0	0
\$001C	Unimplemented									
					-	-			[1
\$001D	IRQ Status and Control Register (INTSCR)	Read: Write:	0	0	0	0	IRQF	0 ACK	IMASK	MODE
	See page 77.	Reset:	0	0	0	0	0	0	0	0
\$001E	Configuration Register 2 (CONFIG2) ⁽¹⁾	Read: Write:	IRQPUD	IRQEN	R	OSCOPT1	OSCOPT0	R	R	RSTEN
	See page 53.	Reset:	0	0	0	0	0	0	0	0 ⁽²⁾
			1. One-time 2. RSTEN re	writable regis set to 0 by a	ter after each power-on res	reset. et (POR) only				
\$001F	Configuration Register 1 (CONFIG1) ⁽¹⁾	Read: Write:	COPRS	LVISTOP	LVIRSTD	LVIPWRD	LVI5OR3	SSREC	STOP	COPD
	See page 54.	Reset:	0	0	0	0	0 ⁽²⁾	0	0	0
			1. One-time 2. LVI5OR3	writable regis reset to 0 by a	ter after each a power-on re	reset. set (POR) on	ly.			
	TIM Status and Control	Read:	TOF	TOIE	TSTOP	0	0	DC2	DQ1	PSO
\$0020	Register (TSC)	Write:	0	TOIL	13101	TRST		1 02	101	1.50
	See page 127.	Reset:	0	0	1	0	0	0	0	0
	TIM Counter Register High	Read:	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8
\$0021	(TCNTH)	Write:								
	See page 120.	Reset:	0	0	0	0	0	0	0	0
				= Unimplem	nented	R	= Reserved	U = Unaf	tected	

Figure 2-2. Control, Status, and Data Registers (Sheet 2 of 5)





2.6.7 Wait Mode

Putting the MCU into wait mode while the FLASH is in read mode does not affect the operation of the FLASH memory directly, but there will not be any memory activity since the CPU is inactive.

The WAIT instruction should not be executed while performing a program or erase operation on the FLASH, or the operation will discontinue and the FLASH will be on standby mode.

2.6.8 Stop Mode

Putting the MCU into stop mode while the FLASH is in read mode does not affect the operation of the FLASH memory directly, but there will not be any memory activity since the CPU is inactive.

The STOP instruction should not be executed while performing a program or erase operation on the FLASH, or the operation will discontinue and the FLASH will be on standby mode

NOTE

Standby mode is the power-saving mode of the FLASH module in which all internal control signals to the FLASH are inactive and the current consumption of the FLASH is at a minimum.



Chapter 3 Analog-to-Digital Converter (ADC)

3.1 Introduction

This section describes the analog-to-digital converter (ADC). The ADC is an 8-bit, 4-channel analog-todigital converter. The ADC module is only available on the MC68HC908QY2, MC68HC908QT2, MC68HC908QY4, and MC68HC908QT4.

3.2 Features

Features of the ADC module include:

- 4 channels with multiplexed input
- · Linear successive approximation with monotonicity
- 8-bit resolution
- Single or continuous conversion
- Conversion complete flag or conversion complete interrupt
- Selectable ADC clock frequency

3.3 Functional Description

Four ADC channels are available for sampling external sources at pins PTA0, PTA1, PTA4, and PTA5. An analog multiplexer allows the single ADC converter to select one of the four ADC channels as an ADC voltage input (ADCVIN). ADCVIN is converted by the successive approximation register-based counters. The ADC resolution is eight bits. When the conversion is completed, ADC puts the result in the ADC data register and sets a flag or generates an interrupt.

Figure 3-2 shows a block diagram of the ADC.

3.3.1 ADC Port I/O Pins

PTA0, PTA1, PTA4, and PTA5 are general-purpose I/O pins that are shared with the ADC channels. The channel select bits (ADC status and control register (ADSCR), \$003C), define which ADC channel/port pin will be used as the input signal. The ADC overrides the port I/O logic by forcing that pin as input to the ADC. The remaining ADC channels/port pins are controlled by the port I/O logic and can be used as general-purpose I/O. Writes to the port register or data direction register (DDR) will not have any affect on the port pin that is selected by the ADC. Read of a port pin which is in use by the ADC will return a 0 if the corresponding DDR bit is at 0. If the DDR bit is at 1, the value in the port data latch is read.



Computer Operating Properly (COP)

The COP counter is a free-running 6-bit counter preceded by the 12-bit system integration module (SIM) counter. If not cleared by software, the COP counter overflows and generates an asynchronous reset after 262,128 or 8176 BUSCLKX4 cycles; depending on the state of the COP rate select bit, COPRS, in configuration register 1. With a 262,128 BUSCLKX4 cycle overflow option, the internal 12.8-MHz oscillator gives a COP timeout period of 20.48 ms. Writing any value to location \$FFFF before an overflow occurs prevents a COP reset by clearing the COP counter and stages 12–5 of the SIM counter.

NOTE

Service the COP immediately after reset and before entering or after exiting stop mode to guarantee the maximum time before the first COP counter overflow.

A COP reset pulls the $\overline{\text{RST}}$ pin low (if the RSTEN bit is set in the CONFIG1 register) for 32 × BUSCLKX4 cycles and sets the COP bit in the reset status register (RSR). See 13.8.1 SIM Reset Status Register.

NOTE

Place COP clearing instructions in the main program and not in an interrupt subroutine. Such an interrupt subroutine could keep the COP from generating a reset even while the main program is not working properly.

6.3 I/O Signals

The following paragraphs describe the signals shown in Figure 6-1.

6.3.1 BUSCLKX4

BUSCLKX4 is the oscillator output signal. BUSCLKX4 frequency is equal to the internal oscillator frequency, the crystal frequency, or the RC-oscillator frequency.

6.3.2 STOP Instruction

The STOP instruction clears the SIM counter.

6.3.3 COPCTL Write

Writing any value to the COP control register (COPCTL) (see 6.4 COP Control Register) clears the COP counter and clears stages 12–5 of the SIM counter. Reading the COP control register returns the low byte of the reset vector.

6.3.4 Power-On Reset

The power-on reset (POR) circuit in the SIM clears the SIM counter $4096 \times BUSCLKX4$ cycles after power up.

6.3.5 Internal Reset

An internal reset clears the SIM counter and the COP counter.

6.3.6 COPD (COP Disable)

The COPD signal reflects the state of the COP disable bit (COPD) in the configuration register 1 (CONFIG1). See Chapter 5 Configuration Register (CONFIG).





6.3.7 COPRS (COP Rate Select)

The COPRS signal reflects the state of the COP rate select bit (COPRS) in the configuration register 1 (CONFIG1). See Chapter 5 Configuration Register (CONFIG).

6.4 COP Control Register

The COP control register (COPCTL) is located at address \$FFFF and overlaps the reset vector. Writing any value to \$FFFF clears the COP counter and starts a new timeout period. Reading location \$FFFF returns the low byte of the reset vector.



Figure 6-2. COP Control Register (COPCTL)

6.5 Interrupts

The COP does not generate CPU interrupt requests.

6.6 Monitor Mode

The COP is disabled in monitor mode when V_{TST} is present on the IRQ pin.

6.7 Low-Power Modes

The WAIT and STOP instructions put the MCU in low power-consumption standby modes.

6.7.1 Wait Mode

The COP continues to operate during wait mode. To prevent a COP reset during wait mode, periodically clear the COP counter.

6.7.2 Stop Mode

Stop mode turns off the BUSCLKX4 input to the COP and clears the SIM counter. Service the COP immediately before entering or after exiting stop mode to ensure a full COP timeout period after entering or exiting stop mode.

6.8 COP Module During Break Mode

The COP is disabled during a break interrupt with monitor mode when BDCOP bit is set in break auxiliary register (BRKAR).



Z — Zero Flag

The CPU sets the zero flag when an arithmetic operation, logic operation, or data manipulation produces a result of \$00.

- 1 = Zero result
- 0 = Non-zero result

C — Carry/Borrow Flag

The CPU sets the carry/borrow flag when an addition operation produces a carry out of bit 7 of the accumulator or when a subtraction operation requires a borrow. Some instructions — such as bit test and branch, shift, and rotate — also clear or set the carry/borrow flag.

1 = Carry out of bit 7

0 = No carry out of bit 7

7.4 Arithmetic/Logic Unit (ALU)

The ALU performs the arithmetic and logic operations defined by the instruction set.

Refer to the *CPU08 Reference Manual* (document order number CPU08RM/AD) for a description of the instructions and addressing modes and more detail about the architecture of the CPU.

7.5 Low-Power Modes

The WAIT and STOP instructions put the MCU in low power-consumption standby modes.

7.5.1 Wait Mode

The WAIT instruction:

- Clears the interrupt mask (I bit) in the condition code register, enabling interrupts. After exit from wait mode by interrupt, the I bit remains clear. After exit by reset, the I bit is set.
- Disables the CPU clock

7.5.2 Stop Mode

The STOP instruction:

- Clears the interrupt mask (I bit) in the condition code register, enabling external interrupts. After exit from stop mode by external interrupt, the I bit remains clear. After exit by reset, the I bit is set.
- Disables the CPU clock

After exiting stop mode, the CPU clock begins running after the oscillator stabilization delay.

7.6 CPU During Break Interrupts

If a break module is present on the MCU, the CPU starts a break interrupt by:

- Loading the instruction register with the SWI instruction
- Loading the program counter with \$FFFC:\$FFFD or with \$FEFC:\$FEFD in monitor mode

The break interrupt begins after completion of the CPU instruction in progress. If the break address register match occurs on the last cycle of a CPU instruction, the break interrupt begins immediately.

A return-from-interrupt instruction (RTI) in the break routine ends the break interrupt and returns the MCU to normal operation if the break interrupt has been deasserted.



again in the SIM and results in the internal bus frequency being one fourth of either the XTALCLK, RCCLK, or INTCLK frequency.

11.5 Low Power Modes

The WAIT and STOP instructions put the MCU in low-power consumption standby modes.

11.5.1 Wait Mode

The WAIT instruction has no effect on the oscillator logic. BUSCLKX2 and BUSCLKX4 continue to drive to the SIM module.

11.5.2 Stop Mode

The STOP instruction disables either the XTALCLK, the RCCLK, or INTCLK output, hence BUSCLKX2 and BUSCLKX4.

11.6 Oscillator During Break Mode

The oscillator continues to drive BUSCLKX2 and BUSCLKX4 when the device enters the break state.

11.7 CONFIG2 Options

Two CONFIG2 register options affect the operation of the oscillator module: OSCOPT1 and OSCOPT0. All CONFIG2 register bits will have a default configuration. Refer to Chapter 5 Configuration Register (CONFIG) for more information on how the CONFIG2 register is used.

Table 11-2 shows how the OSCOPT bits are used to select the oscillator clock source.

 Table 11-2. Oscillator Modes

OSCOPT1	OSCOPT0	Oscillator Modes	
0	0	Internal oscillator	
0	1	External oscillator	
1	0	External RC	
1	1	External crystal	

11.8 Input/Output (I/O) Registers

The oscillator module contains these two registers:

- 1. Oscillator status register (OSCSTAT)
- 2. Oscillator trim register (OSCTRIM)



Oscillator Module (OSC)

11.8.1 Oscillator Status Register

The oscillator status register (OSCSTAT) contains the bits for switching from internal to external clock sources.



Figure 11-4. Oscillator Status Register (OSCSTAT)

ECGON — External Clock Generator On Bit

This read/write bit enables external clock generator, so that the switching process can be initiated. This bit is forced low during reset. This bit is ignored in monitor mode with the internal oscillator bypassed, PTM or CTM mode.

1 = External clock generator enabled

0 = External clock generator disabled

ECGST — External Clock Status Bit

This read-only bit indicates whether or not an external clock source is engaged to drive the system clock.

1 = An external clock source engaged

0 = An external clock source disengaged

11.8.2 Oscillator Trim Register (OSCTRIM)



Figure 11-5. Oscillator Trim Register (OSCTRIM)

TRIM7–TRIM0 — Internal Oscillator Trim Factor Bits

These read/write bits change the size of the internal capacitor used by the internal oscillator. By measuring the period of the internal clock and adjusting this factor accordingly, the frequency of the internal clock can be fine tuned. Increasing (decreasing) this factor by one increases (decreases) the period by approximately 0.2% of the untrimmed period (the period for TRIM = \$80). The trimmed frequency is guaranteed not to vary by more than $\pm 5\%$ over the full specified range of temperature and voltage. The reset value is \$80, which sets the frequency to 12.8 MHz (3.2 MHz bus speed) $\pm 25\%$.

Applications using the internal oscillator should copy the internal oscillator trim value at location \$FFC0 or \$FFC1 into this register to trim the clock source.



A module that is active during wait mode can wake up the CPU with an interrupt if the interrupt is enabled. Stacking for the interrupt begins one cycle after the WAIT instruction during which the interrupt occurred. In wait mode, the CPU clocks are inactive. Refer to the wait mode subsection of each module to see if the module is active or inactive in wait mode. Some modules can be programmed to be active in wait mode.

Wait mode can also be exited by a reset (or break in emulation mode). A break interrupt during wait mode sets the SIM break stop/wait bit, SBSW, in the break status register (BSR). If the COP disable bit, COPD, in the configuration register is 0, then the computer operating properly module (COP) is enabled and remains active in wait mode.

Figure 13-15 and Figure 13-16 show the timing for wait recovery.





13.7.2 Stop Mode

In stop mode, the SIM counter is reset and the system clocks are disabled. An interrupt request from a module can cause an exit from stop mode. Stacking for interrupts begins after the selected stop recovery time has elapsed. Reset or break also causes an exit from stop mode.

The SIM disables the oscillator signals (BUSCLKX2 and BUSCLKX4) in stop mode, stopping the CPU and peripherals. Stop recovery time is selectable using the SSREC bit in the configuration register 1 (CONFIG1). If SSREC is set, stop recovery is reduced from the normal delay of 4096 BUSCLKX4 cycles down to 32. This is ideal for the internal oscillator, RC oscillator, and external oscillator options which do not require long start-up times from stop mode.

NOTE

External crystal applications should use the full stop recovery time by clearing the SSREC bit.

Development Support



RST, IRQ: Pins have internal (about 30K Ohms) pull up

PTA[0:5]: High current sink and source capability

PTA[0:5]: Pins have programmable keyboard interrupt and pull up

PTB[0:7]: Not available on 8-pin devices – MC68HC908QT1, MC68HC908QT2, and MC68HC908QT4 (see note in 12.1 Introduction)

ADC: Not available on the MC68HC908QY1 and MC68HC908QT1

Figure 15-1. Block Diagram Highlighting BRK and MON Blocks







Development Support

15.2.2.1 Break Status and Control Register

The break status and control register (BRKSCR) contains break module enable and status bits.



Figure 15-3. Break Status and Control Register (BRKSCR)

BRKE — Break Enable Bit

This read/write bit enables breaks on break address register matches. Clear BRKE by writing a 0 to bit 7. Reset clears the BRKE bit.

1 = Breaks enabled on 16-bit address match

0 = Breaks disabled

BRKA — Break Active Bit

This read/write status and control bit is set when a break address match occurs. Writing a 1 to BRKA generates a break interrupt. Clear BRKA by writing a 0 to it before exiting the break routine. Reset clears the BRKA bit.

1 = Break address match

0 = No break address match

15.2.2.2 Break Address Registers

The break address registers (BRKH and BRKL) contain the high and low bytes of the desired breakpoint address. Reset clears the break address registers.



Figure 15-4. Break Address Register High (BRKH)



Figure 15-5. Break Address Register Low (BRKL)



15.3.1 Functional Description

Figure 15-9 shows a simplified diagram of monitor mode entry.

The monitor module receives and executes commands from a host computer. Figure 15-10, Figure 15-11, and Figure 15-12 show example circuits used to enter monitor mode and communicate with a host computer via a standard RS-232 interface.



Figure 15-9. Simplified Monitor Mode Entry Flowchart



Development Support





Table 15-5. IREAD (Indexed Read) Command



Table 15-6. IWRITE (Indexed Write) Command



A sequence of IREAD or IWRITE commands can access a block of memory sequentially over the full 64-Kbyte memory map.



Electrical Specifications

16.3 Functional Operating Range

Characteristic	Symbol	Value	Unit	Temp. Code
Operating temperature range	T _A	-40 to +125 -40 to +105 -40 to +85	•C	M V C
Operating voltage range	V _{DD}	2.7 to 5.5	V	—

16.4 Thermal Characteristics

Characteristic	Symbol	Value	Unit
Thermal resistance 8-pin PDIP 8-pin SOIC 8-pin DFN 16-pin PDIP 16-pin SOIC 16-pin TSSOP	θ _{JA}	105 142 173 76 90 133	•C/W
I/O pin power dissipation	P _{I/O}	User determined	W
Power dissipation ⁽¹⁾	P _D	$P_D = (I_{DD} \times V_{DD})$ + $P_{I/O} = K/(T_J + 273 \bullet C)$	W
Constant ⁽²⁾	к	$P_{D} x (T_{A} + 273 \bullet C) + P_{D}^{2} x \theta_{JA}$	W/•C
Average junction temperature	Τ _J	$T_A + (P_D \times \theta_{JA})$	•C
Maximum junction temperature	T _{JM}	150	•C

1. Power dissipation is a function of temperature.

2. K constant unique to the device. K can be determined for a known T_A and measured P_D . With this value of K, P_D and T_J can be determined for any value of T_A .



16.11 3-V Control Timing

Characteristic ⁽¹⁾	Symbol	Min	Max	Unit
Internal operating frequency	f _{OP} (f _{Bus})	_	4	MHz
Internal clock period (1/f _{OP})	t _{cyc}	250	_	ns
RST input pulse width low	t _{RL}	200		ns
IRQ interrupt pulse width low (edge-triggered)	t _{ILIH}	200	-	ns
IRQ interrupt pulse period	t _{ILIL}	Note ⁽²⁾		t _{cyc}

1. V_{DD} = 2.7 to 3.3 Vdc, V_{SS} = 0 Vdc, T_A = T_L to T_H; timing shown with respect to 20% V_{DD} and 70% V_{DD}, unless otherwise noted.

2. The minimum period is the number of cycles it takes to execute the interrupt service routine plus 1 t_{cyc} .



Figure 16-7. RST and IRQ Timing

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NOTES:

- 1. DIMENSIONS ARE IN MILLIMETERS.
- 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- 3. DATUMS A AND B TO BE DETERMINED AT THE PLANE WHERE THE BOTTOM OF THE LEADS EXIT THE PLASTIC BODY.
- 4. THIS DIMENSION DOES NOT INCLUDE MOLD FLASH, PROTRUSION OR GATE BURRS. MOLD FLASH, PROTRUSION OR GATE BURRS SHALL NOT EXCEED 0.15 MM PER SIDE. THIS DIMENSION IS DETERMINED AT THE PLANE WHERE THE BOTTOM OF THE LEADS EXIT THE PLASTIC BODY.
- 5. THIS DIMENSION DOES NOT INCLUDE INTER-LEAD FLASH OR PROTRUSIONS. INTER-LEAD FLASH AND PROTRUSIONS SHALL NOT EXCEED 0.25 MM PER SIDE. THIS DIMENSION IS DETERMINED AT THE PLANE WHERE THE BOTTOM OF THE LEADS EXIT THE PLASTIC BODY.
- 6. THIS DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED 0.62 mm.

TITLE:	CASE NUMBER: 751G-05
16LD SOIC W/B, 1.27 PIICH,	STANDARD: JEDEC MS-013AA
	PACKAGE CODE: 2003 SHEET: 2 OF 3

